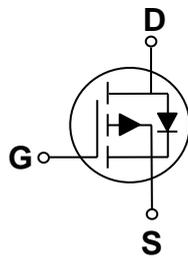


## 20V P-Channel MOSFETs

### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK3X3 Pin Configuration



BVDSS	RDSON	ID
-20V	8mΩ	-60A

### Features

- -20V,-60A, RDS(ON) =8mΩ@VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Networking
- Hand-Held Instruments

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>GS</sub>	Gate-Source Voltage	± 12	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	-60	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	-38	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-240	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	62.5	W
	Power Dissipation – Derate above 25°C	0.5	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	2	°C/W



# FTK2603Z

## 20V P-Channel MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$  , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.01	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-20V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu A$
		$V_{DS}=-16V$ , $V_{GS}=0V$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 12V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V$ , $I_D=-8A$	---	6	8	m $\Omega$
		$V_{GS}=-2.5V$ , $I_D=-5A$	---	8	11	
		$V_{GS}=-1.8V$ , $I_D=-3A$	---	11	16	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu A$	-0.3	-0.6	-1.0	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V$ , $I_S=-5A$	---	20	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=-10V$ , $V_{GS}=-4.5V$ , $I_D=-5A$	---	44.4	80	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	7.2	14	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	10.2	20	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=-10V$ , $V_{GS}=-4.5V$ , $R_G=25\Omega$ $I_D=-1A$	---	13.2	26	nS
$T_r$	Rise Time <sup>2,3</sup>		---	68	120	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	160	320	
$T_f$	Fall Time <sup>2,3</sup>		---	154	300	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V$ , $V_{GS}=0V$ , $F=1\text{MHz}$	---	4060	8000	pF
$C_{oss}$	Output Capacitance		---	520	1000	
$C_{rss}$	Reverse Transfer Capacitance		---	400	800	

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-60	A
$I_{SM}$	Pulsed Source Current		---	---	-120	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V$ , $I_S=-1A$ , $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## Typical Performance Characteristics

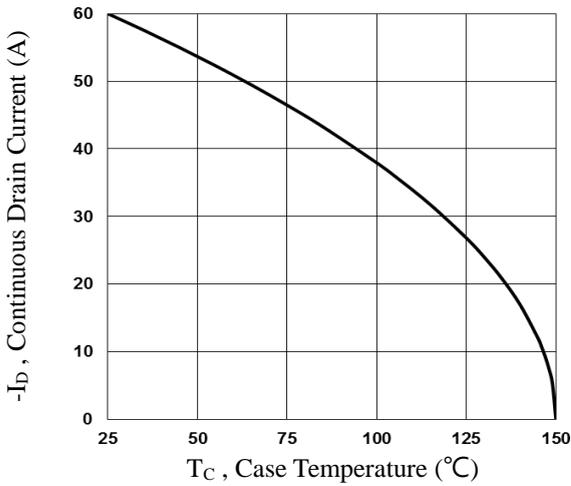


Fig.1 Continuous Drain Current vs.  $T_C$

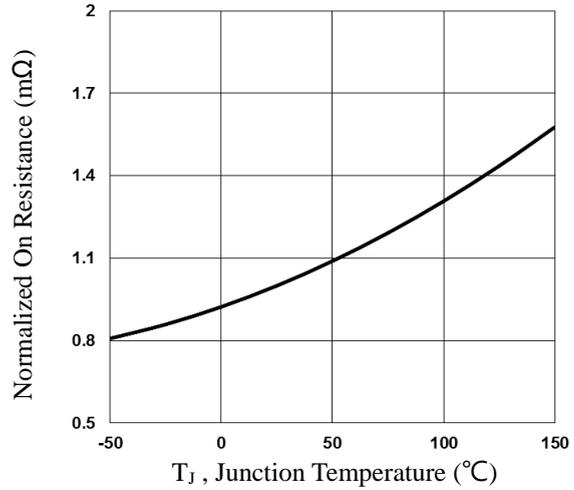


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

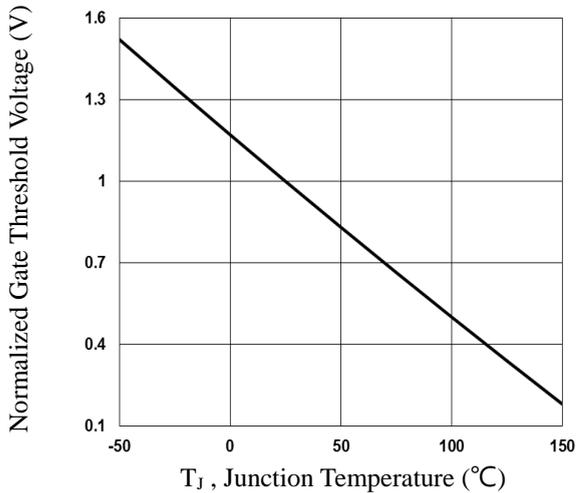


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

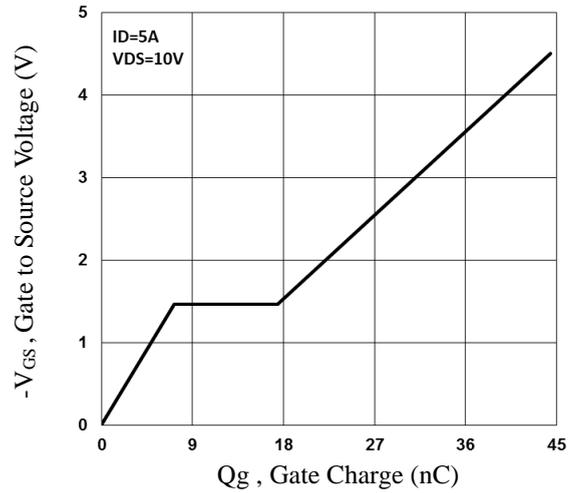


Fig.4 Gate Charge Waveform

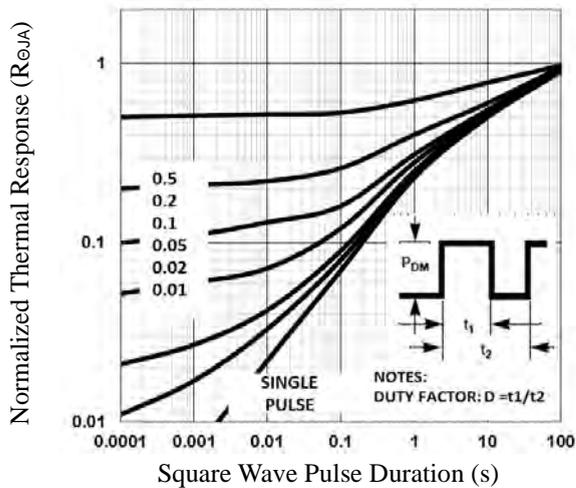


Fig.5 Normalized Transient Response

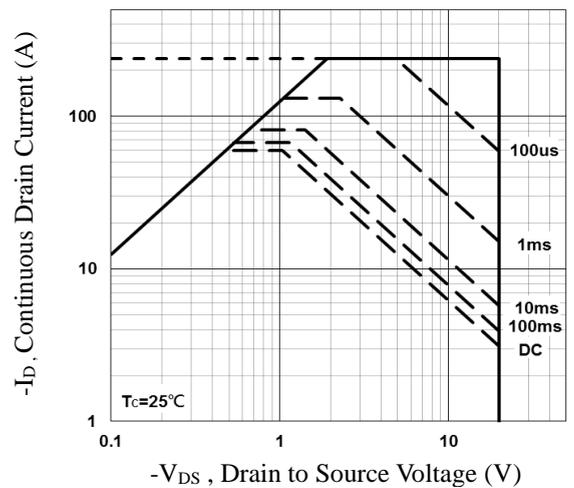


Fig.6 Maximum Safe Operation Area

## Typical Performance Characteristics(Con.)

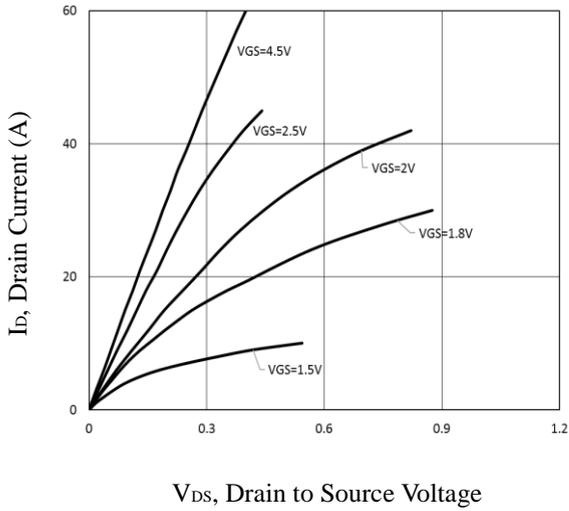


Fig.7 Typical Output Characteristics

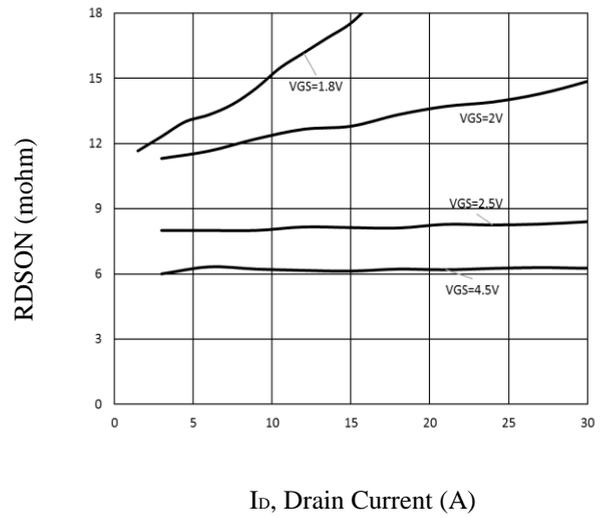


Fig.8 RDS(on) vs. Drain Current

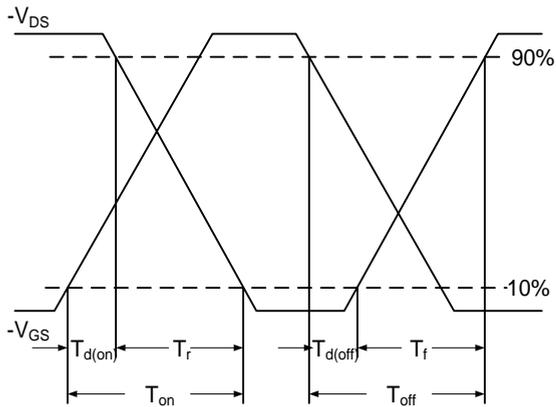


Fig.9 Switching Time Waveform

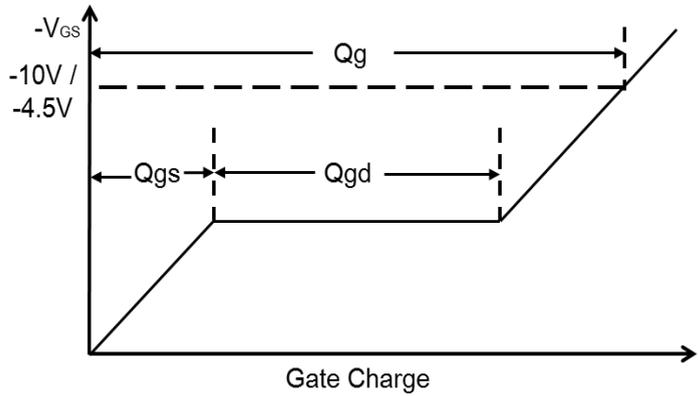
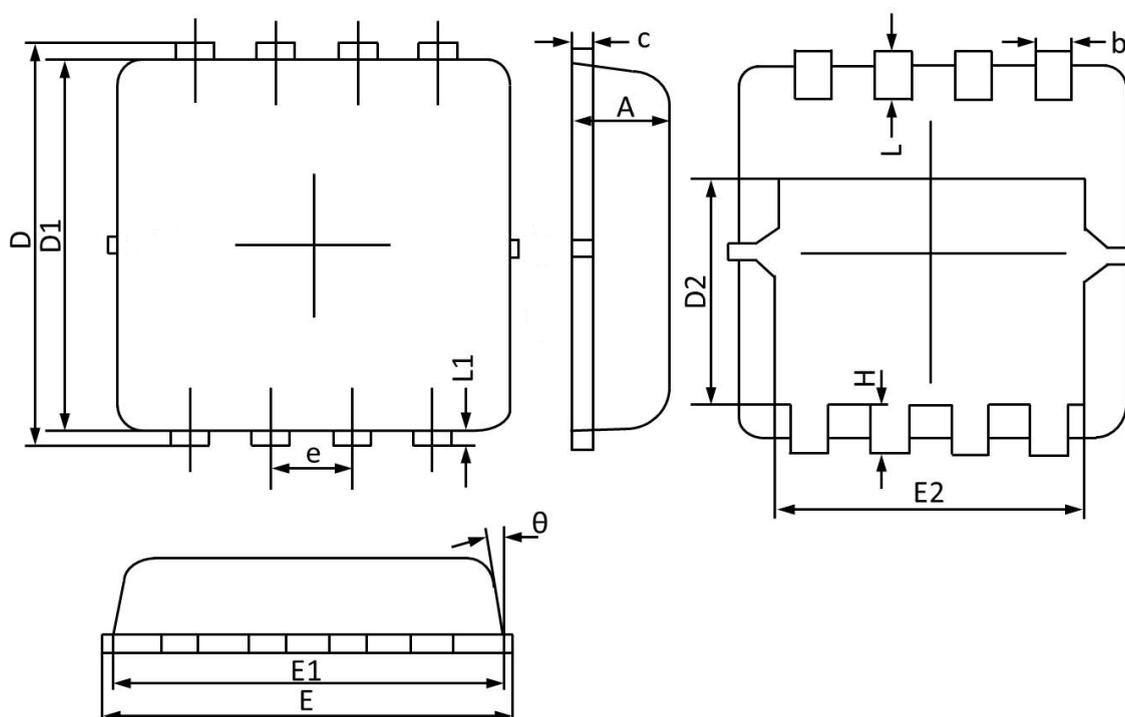


Fig.10 Gate Charge Waveform

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°